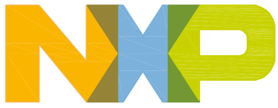

PIN 1 INDEX AREA

7

A

DETAIL E

4X ⌓ 0.1 C

7

B

4.8
4.6

⌖ 0.1 C A B

EXPOSED DIE ATTACH PAD

9 16

8 17

28X 0.65

0.325

4.8
4.6

⌖ 0.1 C A B

1 24

32X 0.35
0.25

0.35±0.1 X 45°
PIN 1 ID

32 25

⌖ 0.1Ⓜ C A B
0.05Ⓜ C

32X 0.6
0.5

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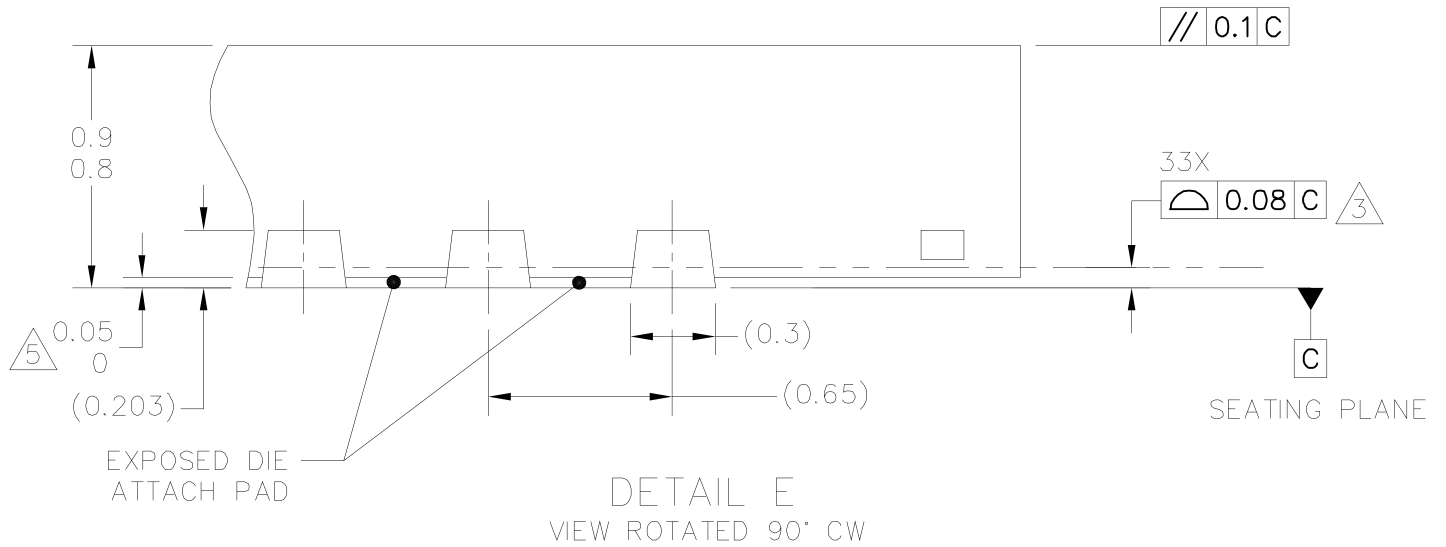
TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.65 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00706D	REV: A
	STANDARD: NON-JEDEC	
	SOT865-4	12 JAN 2016



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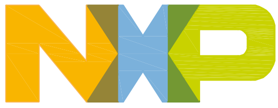
	STANDARD: NON-JEDEC
	SOT865-4 12 JAN 2016



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M—1994.
3. COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
4. MIN METAL GAP SHOULD BE 0.2MM.
5. THIS DIMENSION APPLIES ONLY FOR TERMINALS.

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